

#### P-CHANNEL ENHANCEMENT MODE MOSFET

### **Product Summary**

BV <sub>DSS</sub>	R <sub>DS(ON)</sub> Max	I <sub>D</sub> Max T <sub>A</sub> = +25°C
-30V	19mΩ @ Vgs = -10V	-8.6A
-307	45mΩ @ VGS = -4.5V	-5.5A

### **Description and Applications**

This MOSFET is designed to minimize the on-state resistance (R<sub>DS(ON)</sub>), yet maintain superior switching performance, making it ideal for high efficiency power management applications.

- Battery Management Application
- Power Management Functions
- DC-DC Converters

### **Features and Benefits**

- 0.6mm Profile Ideal for Low Profile Applications
- Low Gate Threshold Voltage
- Low On-Resistance
- ESD Protected Gate
- Totally Lead-Free & Fully RoHS Compliant (Notes 1 & 2)
- Halogen and Antimony Free. "Green" Device (Note 3)
- For automotive applications requiring specific change control (i.e.: parts qualified to AEC-Q100/101/200, PPAP capable, and manufactured in IATF 16949 certified facilities), please refer to the related automotive grade (Q-suffix) part. A listing can be found at

https://www.diodes.com/products/automotive/automotive-products/.

 This part is qualified to JEDEC standards (as references in AEC-Q) for High Reliability.

https://www.diodes.com/quality/product-definitions/

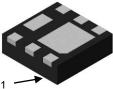
#### **Mechanical Data**

- Case: U-DFN2020-6
- Case Material: Molded Plastic, "Green" Molding Compound.
  UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020
- Terminals: Finish NiPdAu over Copper Leadframe. Solderable per MIL-STD-202, Method 208 @
- Weight: 0.007 grams (Approximate)

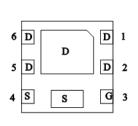




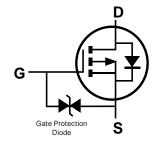




Top View Bottom View



Pin Out Bottom View



**Equivalent Circuit** 

### **Ordering Information** (Note 4)

Part Number	Case	Packaging
DMP3026SFDF-7	U-DFN2020-6 (Type F)	3,000/Tape & Reel
DMP3026SFDF-13	U-DFN2020-6 (Type F)	10.000/Tape & Reel

Notes:

- 1. No purposely added lead. Fully EU Directive 2002/95/EC (RoHS), 2011/65/EU (RoHS 2) & 2015/863/EU (RoHS 3) compliant.
- 2. See https://www.diodes.com/quality/lead-free/ for more information about Diodes Incorporated's definitions of Halogen- and Antimony-free, "Green" and Lead-free.
- 3. Halogen- and Antimony-free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.
- 4. For packaging details, go to our website at https://www.diodes.com/design/support/packaging/diodes-packaging/.



## **Marking Information**

Site 1



6P = Product Type Marking Code YM = Date Code Marking Y = Year (ex: H = 2020) M = Month (ex: 9 = September)

Date Code Key

Year	2016		2020	2021	2022	2023	2024	2025	2026	2027	2028	2029
Code	D		Н	I	J	K	L	M	N	0	Р	R
Month	Jan	Feb	Mar	Apr	May	Jun	Jul	Aug	Sep	Oct	Nov	Dec

Site 2



6P = Product Type Marking Code YWX = Date Code Marking Y = Year (ex: 0 = 2020) W = Week (ex: a = week 27; z Represents Week 52 and 53) X = Internal Code (ex: U = Monday)

Date Code Key

rear	2016	•••	2020	2021	2022	2023	2024	2025	2026	2027	2028	2029
Code	6		0	1	2	3	4	5	6	7	8	9

I	Week	1-26	27-52	53
	Code	A-Z	a-z	Z

Internal Code	Sun	Mon	Tue	Wed	Thu	Fri	Sat
Code	Т	U	V	W	X	Υ	Z



## **Maximum Ratings** (@T<sub>A</sub> = +25°C, unless otherwise specified.)

Characteristic	Symbol	Value	Unit		
Drain-Source Voltage	VDSS	-30	V		
Gate-Source Voltage	Vgss	±25	V		
Continuous Durin Courset (Note C) V 40V	Steady State	T <sub>A</sub> = +25°C T <sub>A</sub> = +70°C	lo	-8.6 -6.9	А
Continuous Drain Current (Note 6) Vgs = -10V	t<10s	T <sub>A</sub> = +25°C T <sub>A</sub> = +70°C	lo	-10.3 -8.3	А
Pulsed Drain Current (10µs Pulse, Duty Cycle = 1%)	)		I <sub>DM</sub>	-50	Α
Continuous Source-Drain Diode Current (Note 6)		$T_A = +25$ °C	Is	-2.0	Α
Avalanche Current (Note 7) L = 0.1mH	las	-23	А		
Avalanche Energy (Note 7) L = 0.1mH			Eas	27	mJ

## Thermal Characteristics (@TA = +25°C, unless otherwise specified.)

Characteristic		Symbol	Value	Unit	
Total Bower Discinction (Note 5)	T <sub>A</sub> = +25°C	D-	0.71	W	
Total Power Dissipation (Note 5)	T <sub>A</sub> = +70°C	PD	0.47	VV	
Thermal Resistance, Junction to Ambient (Note 5)	Steady State	Rеja	178	°C/W	
memial Resistance, Junction to Ambient (Note 5)	t<10s	Көја	125	C/VV	
Total Power Dissipation (Note 6)	$T_A = +25$ °C	T <sub>A</sub> = +25°C		W	
Total Power Dissipation (Note 6)	T <sub>A</sub> = +70°C	$P_D$	1.3	VV	
Thermal Resistance, Junction to Ambient (Note 6)	Steady State	D	62		
memial Resistance, Junction to Ambient (Note 6)	t<10s	$R_{\theta JA}$	43	°C/W	
Thermal Resistance, Junction to Case (Note 6)	Steady State	Rejc	7.4		
Operating and Storage Temperature Range		$T_{J_i} T_{STG}$	-55 to +150	°C	

Notes:

- 5. Device mounted on FR-4 substrate PC board, 2oz copper, with minimum recommended pad layout.
- 6. Device mounted on FR-4 substrate PC board, 2oz copper, with 1-inch square copper plate.
- 7. IAS and EAS ratings are based on low frequency and duty cycles to keep  $T_J = +25$ °C.



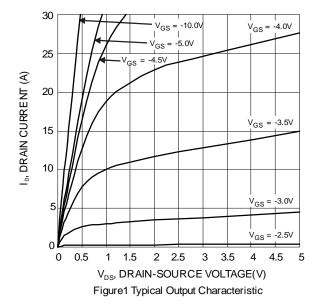
# **Electrical Characteristics** (@T<sub>A</sub> = +25°C, unless otherwise specified.)

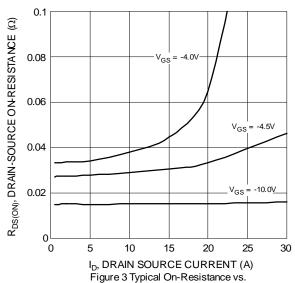
Characteristic	Symbol	Min	Тур	Max	Unit	Test Condition	
OFF CHARACTERISTICS (Note 8)							
Drain-Source Breakdown Voltage	BVDSS	-30	_	_	V	$Vgs = 0V, I_D = -250\mu A$	
Zero Gate Voltage Drain Current T <sub>J</sub> = +25°C	1	_	_	-1		\/ 24\/ \/ 0\/	
Zero Gate Voltage Drain Current T <sub>J</sub> = +150°C (Note 9)	IDSS	_	_	-100	μA	VDS = -24V, VGS = 0V	
Gate-Source Leakage	Igss	_	_	±10	μA	$VGS = \pm 25V$ , $VDS = 0V$	
ON CHARACTERISTICS (Note 8)							
Gate Threshold Voltage	Vgs(TH)	-1	_	-3	V	$V_{DS} = V_{GS}$ , $I_D = -250\mu A$	
			15	19		VGS = -10V, ID = -4.5A	
Static Drain-Source On-Resistance	RDS(ON)		28	45	mΩ	VGS = -4.5V, $ID = -3.5A$	
			34	54		VGS = -4.0V, ID = -3.0A	
Diode Forward Voltage	$V_{SD}$	l	-0.7	-1.2	V	$V_{GS} = 0V, I_{S} = -1.0A$	
DYNAMIC CHARACTERISTICS (Note 9)							
Input Capacitance	C <sub>ISS</sub>	_	1,204	_		\\ 45\\ \\ 0\\	
Output Capacitance	Coss	_	154	_	pF	$V_{DS} = -15V, V_{GS} = 0V,$ f = 1.0MHz	
Reverse Transfer Capacitance	Crss	_	112	_		I = I.UIVIDZ	
Gate Resistance	R <sub>G</sub>	-	16	_	Ω	$V_{DS} = 0V$ , $V_{GS} = 0V$ , $f = 1MHz$	
Total Gate Charge (V <sub>GS</sub> = -10V)	Q <sub>G</sub>	_	19.6	_			
Total Gate Charge (V <sub>GS</sub> = -4.5V)	$Q_G$	_	9.2	_	nC	\/== 45\/ I= 0.5A	
Gate-Source Charge	Qgs		4.3	_	nc nc	$V_{DS} = -15V, I_{D} = -9.5A$	
Gate-Drain Charge	Q <sub>GD</sub>	_	3.9	_			
Turn-On Delay Time	tD(ON)		5.3	_			
Turn-On Rise Time	t <sub>R</sub>	_	23	_		V <sub>DS</sub> = -15V, V <sub>GS</sub> = -10V,	
Turn-Off Delay Time	t <sub>D(OFF)</sub>	_	34	_	ns	$R_G = 6\Omega, I_D = -9.5A$	
Turn-Off Fall Time	tF	_	26	_			
Reverse Recovery Time	trr	_	10	_	ns	1 0 5 A 11/14 400 A /	
Reverse Recovery Charge	Q <sub>RR</sub>	_	3.3	_	nC	$I_F = -9.5A$ , di/dt = 100A/ $\mu$ s	

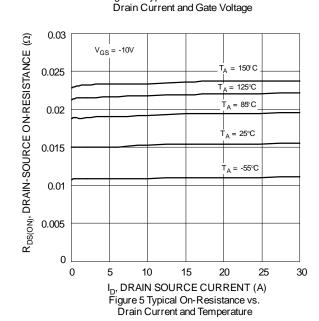
Notes:

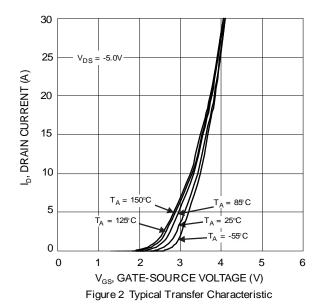
Short duration pulse test used to minimize self-heating effect.
 Guaranteed by design. Not subject to product testing.

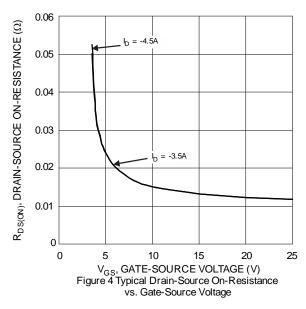












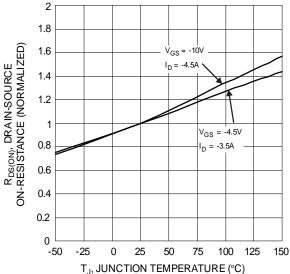
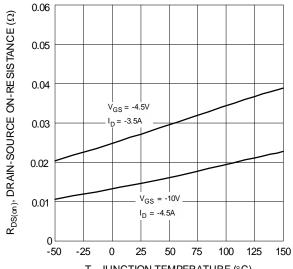


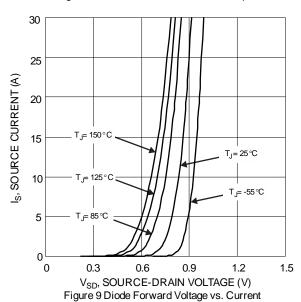
Figure 6 On-Resistance Variation with Temperature

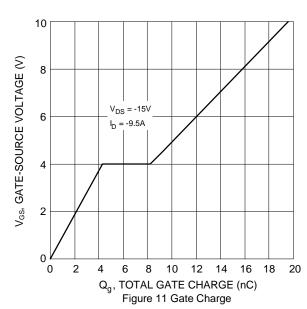






T<sub>J</sub>, JUNCTION TEMPERATURE (°C) Figure 7 On-Resistance Variation with Temperature





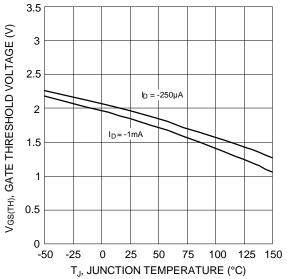
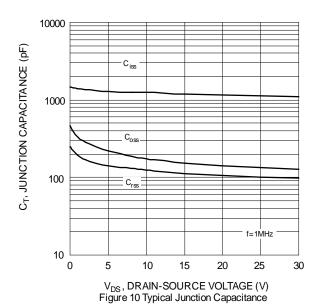
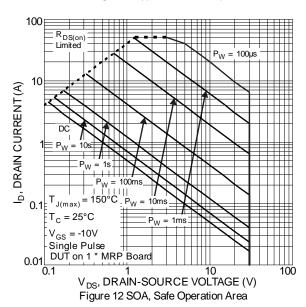
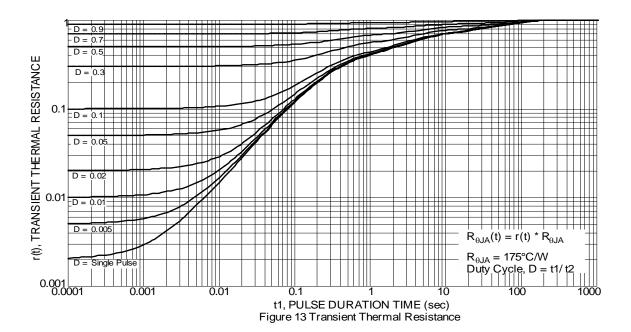


Figure 8 Gate Threshold Variation vs. Junction Temperature







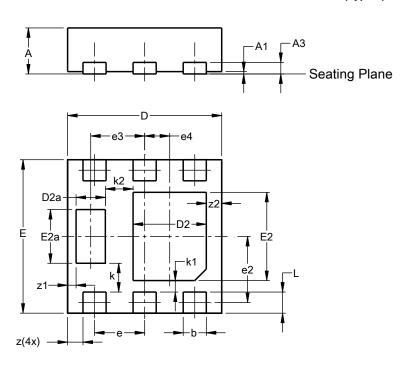




## **Package Outline Dimensions**

Please see http://www.diodes.com/package-outlines.html for the latest version.

#### U-DFN2020-6 (Type F)

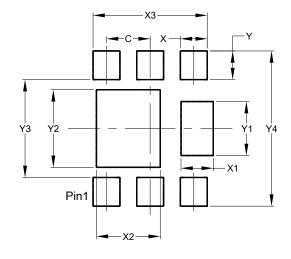


U-DFN2020-6								
		pe F)						
Dim	Min	Max	Тур					
Α	0.57	0.57 0.63 0.60						
A1	0.00 0.05 0.03							
A3	-	-	0.15					
b	0.25	0.35	0.30					
D	1.95	2.05	2.00					
D2	0.85	1.05	0.95					
D2a	0.33							
E	1.95 2.05 2.00							
E2	1.05	1.25	1.15					
E2a	0.65	0.75	0.70					
е		0.65 BS	С					
e2	(	).863 BS	SC S					
е3		0.70 BS	С					
e4	(	).325 BS	SC S					
k		0.37 BS	С					
k1		0.15 BS	С					
k2		0.36 BS	С					
L		0.325						
Z	0.20 BSC							
<b>z</b> 1	(	).110 BS	SC SC					
z2		0.20 BS	С					
All C	imens	ions in	mm					

# **Suggested Pad Layout**

Please see http://www.diodes.com/package-outlines.html for the latest version.

#### U-DFN2020-6 (Type F)



Dimensions	Value (in mm)		
С	0.650		
Х	0.400		
X1	0.480		
X2	0.950		
Х3	1.700		
Y	0.425		
Y1	0.800		
Y2	1.150		
Y3	1.450		
Y4	2.300		



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